

FIG. 1

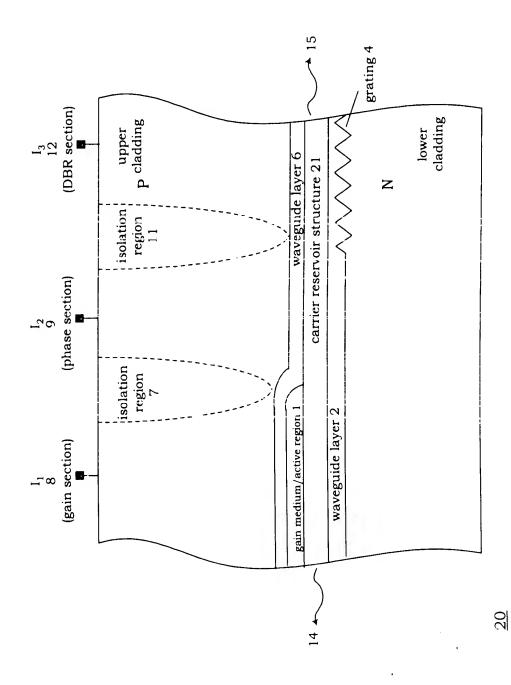


FIG. 2

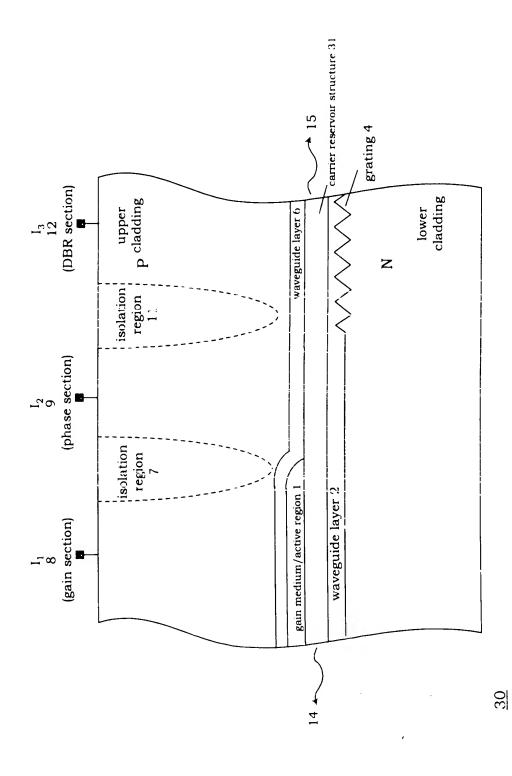


FIG. 3

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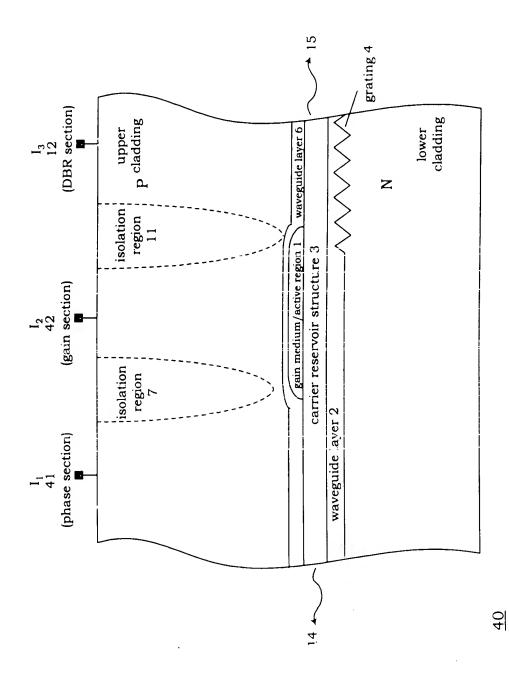


FIG. 4

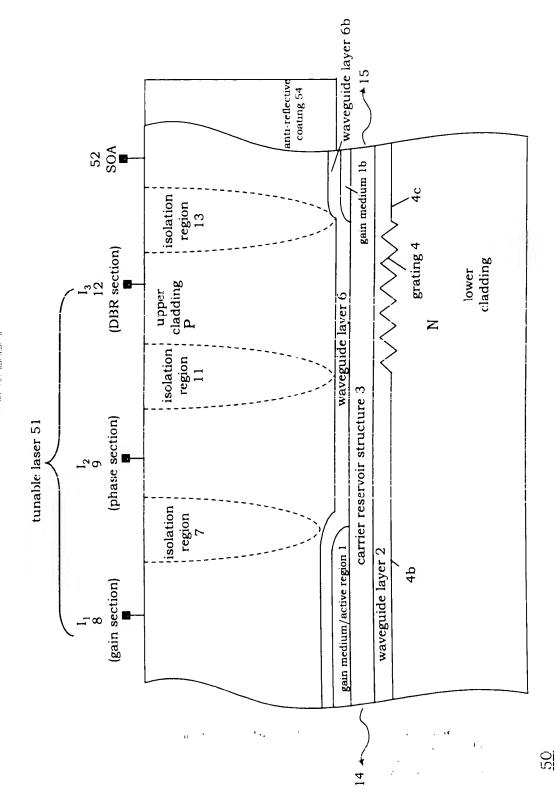


FIG. 5

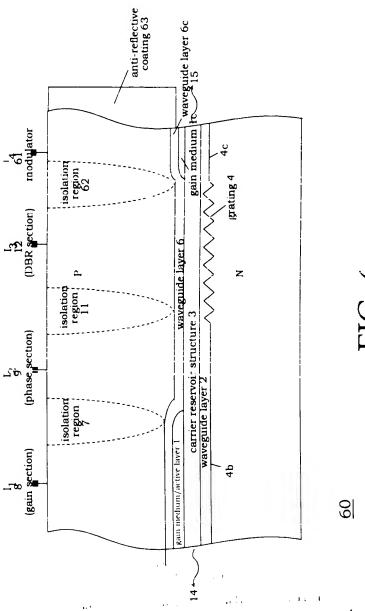
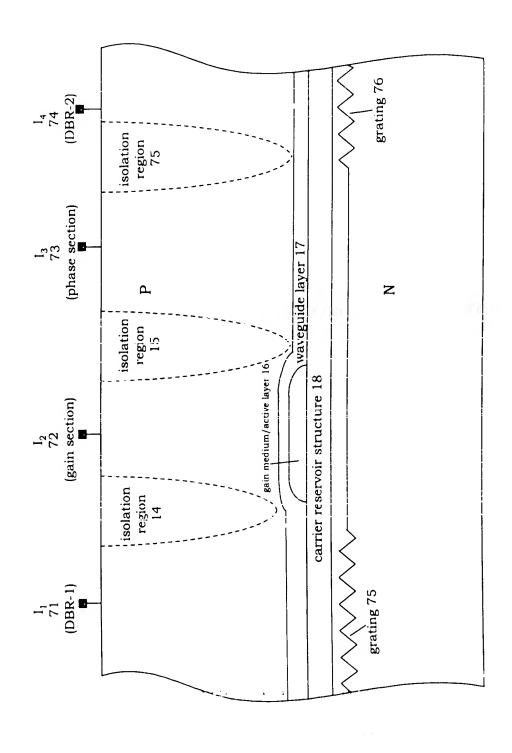
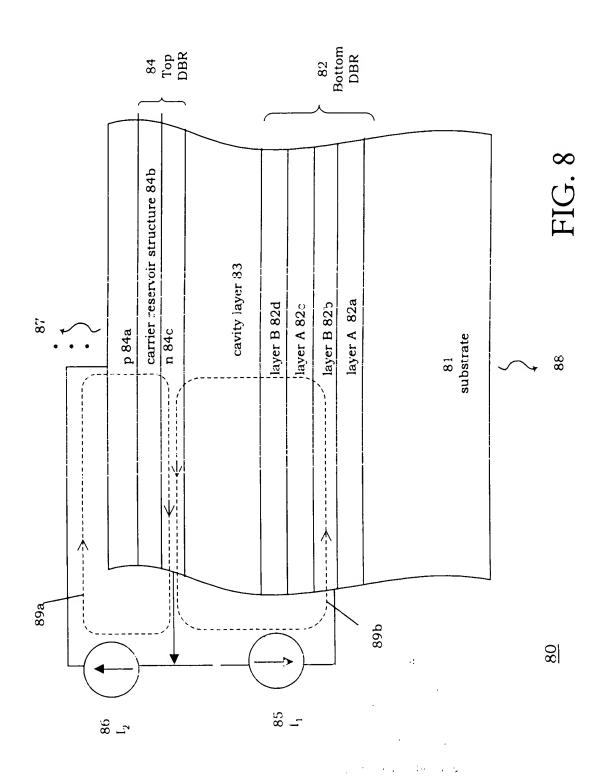
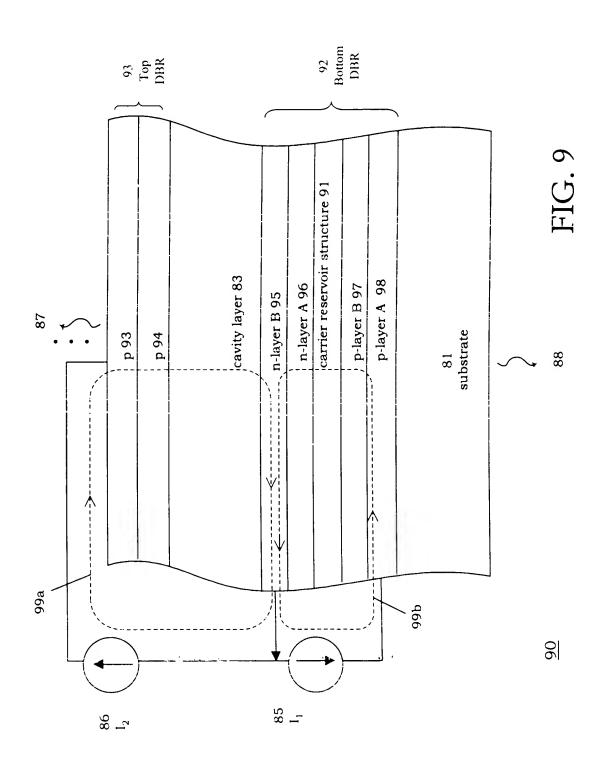


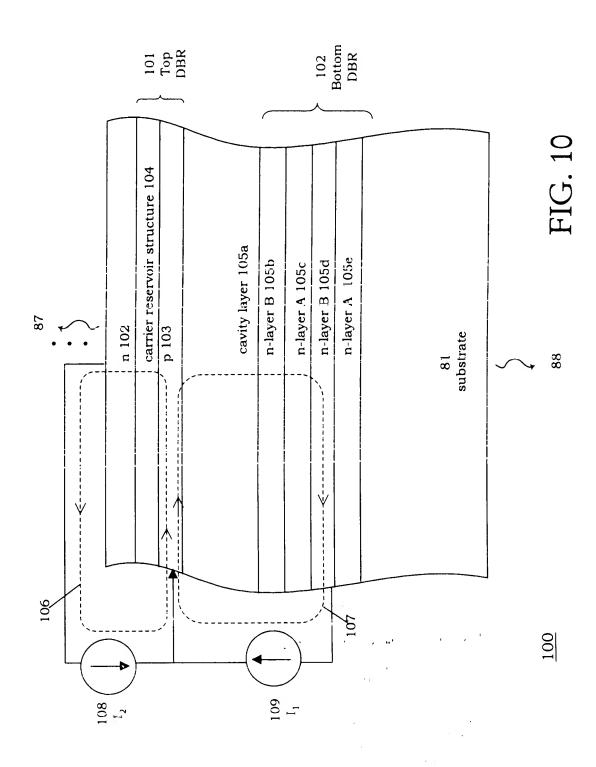
FIG. 6

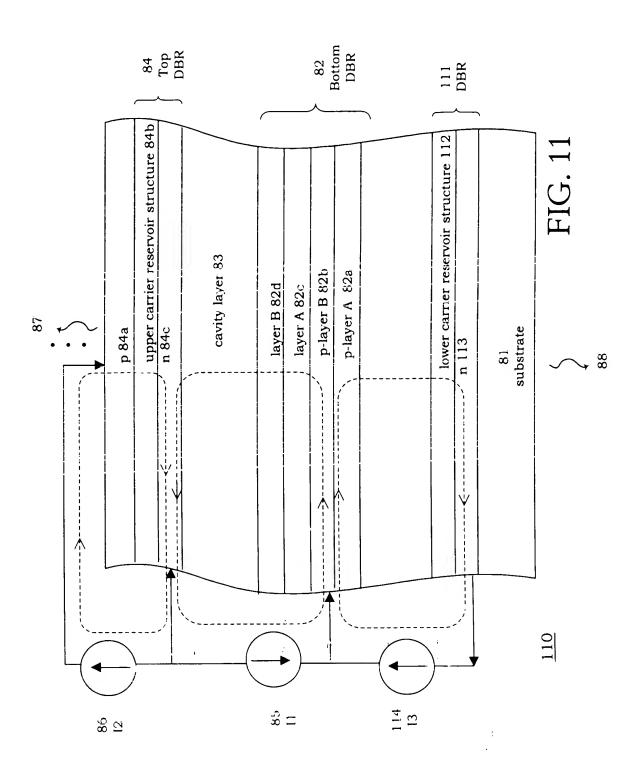


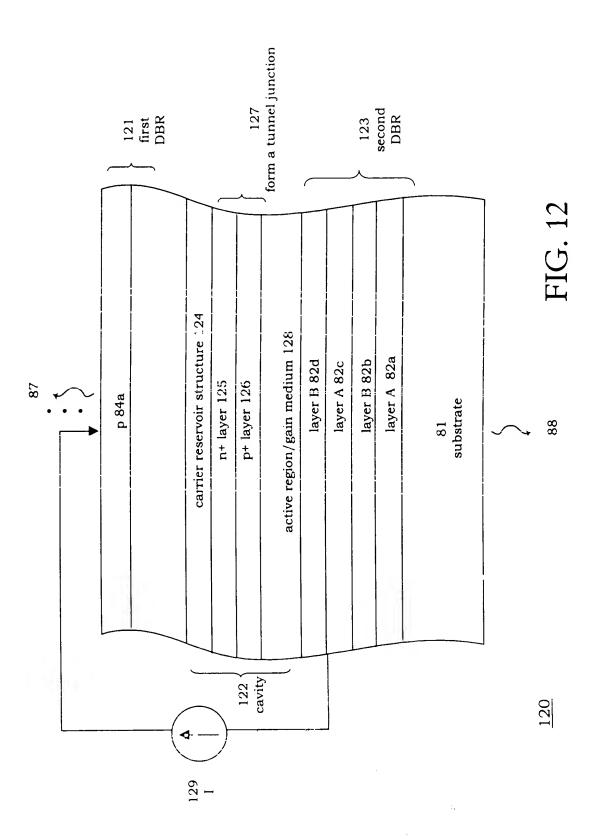
FIG

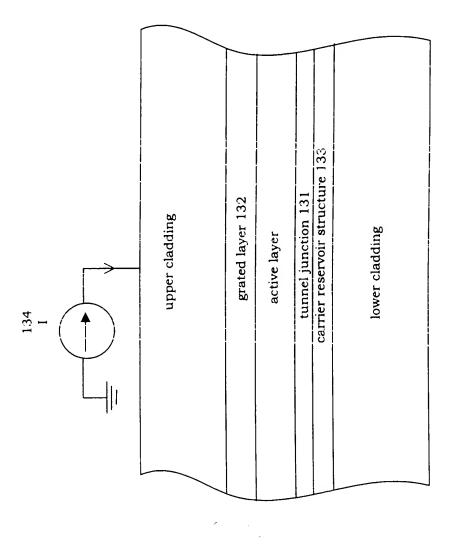












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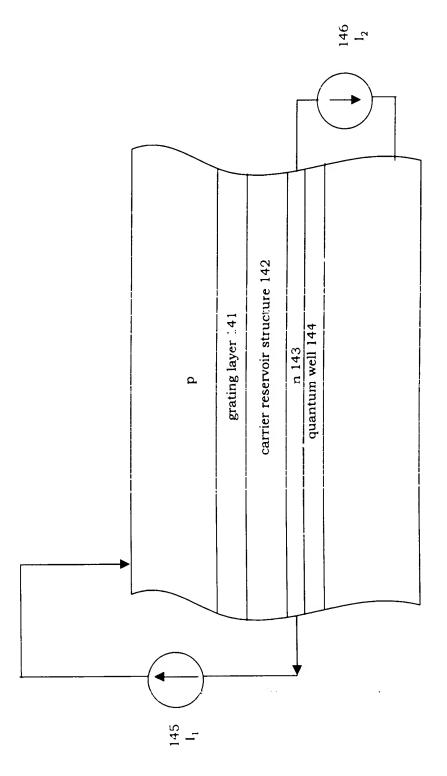
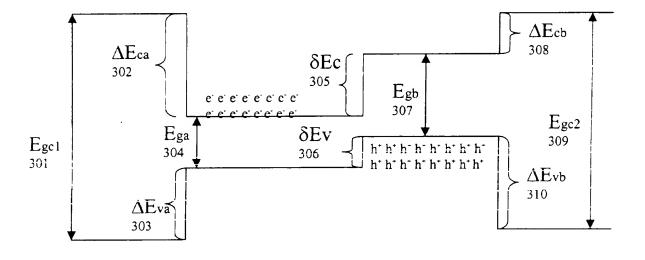


FIG. 14



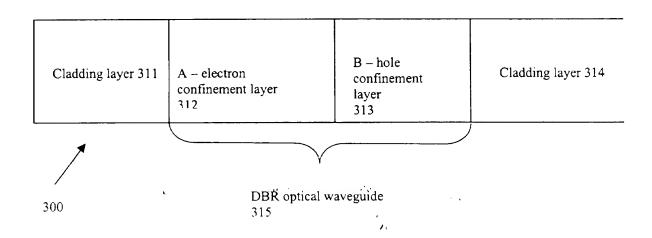
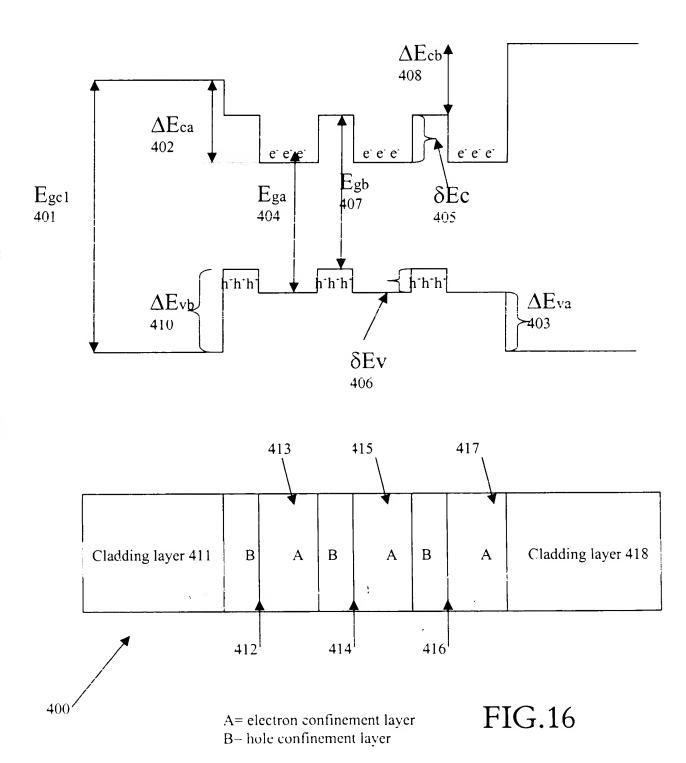
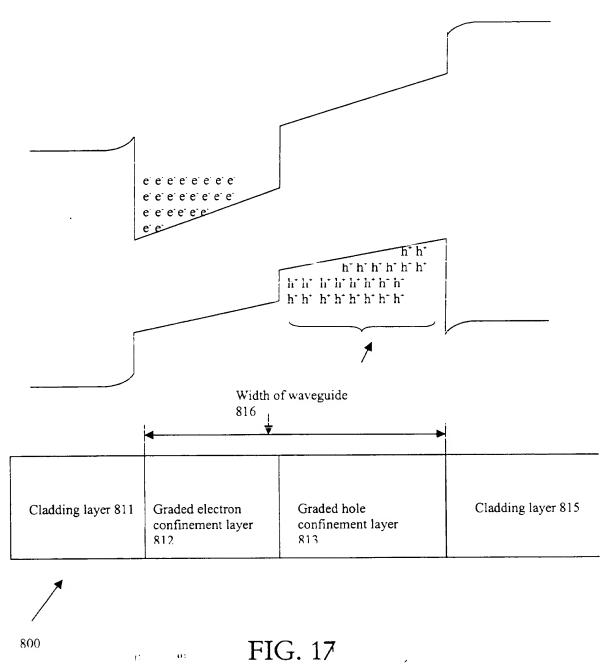
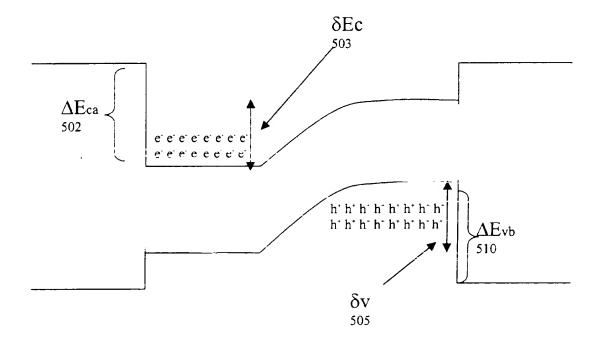


FIG. 15







conf	electron Graded inement layer 513 r 512 A → B	B - hole confinement layer 514	Cladding layer 515
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500

FIG. 18

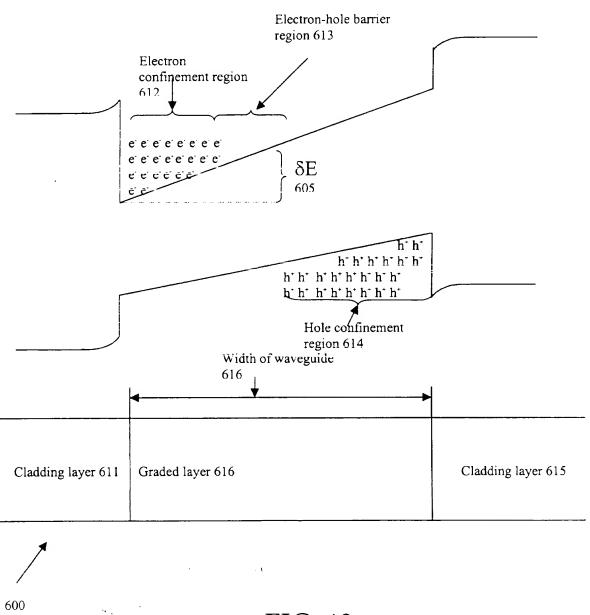


FIG. 19

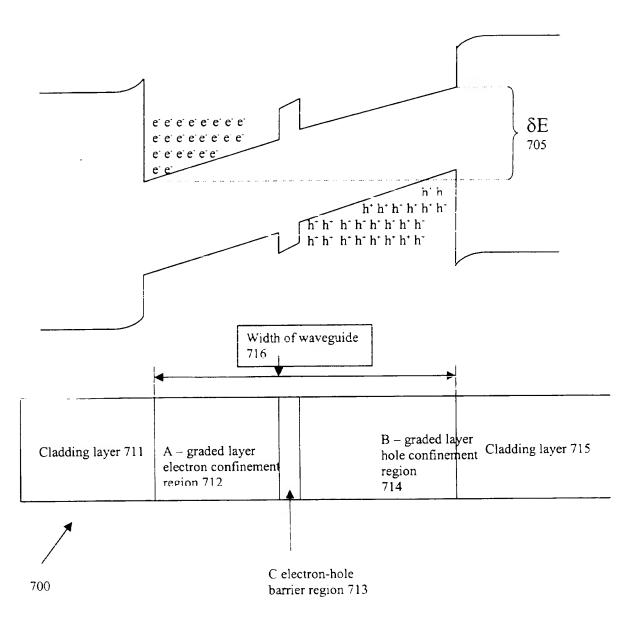


FIG. 20

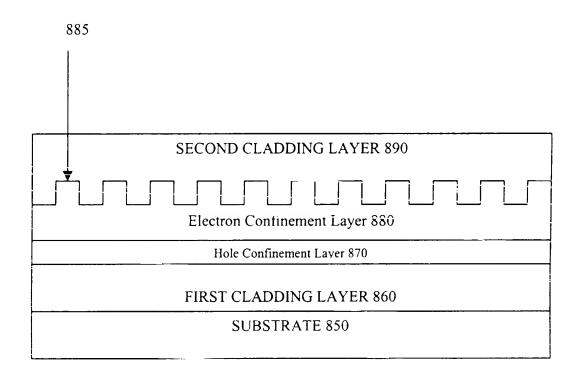


FIG. 21

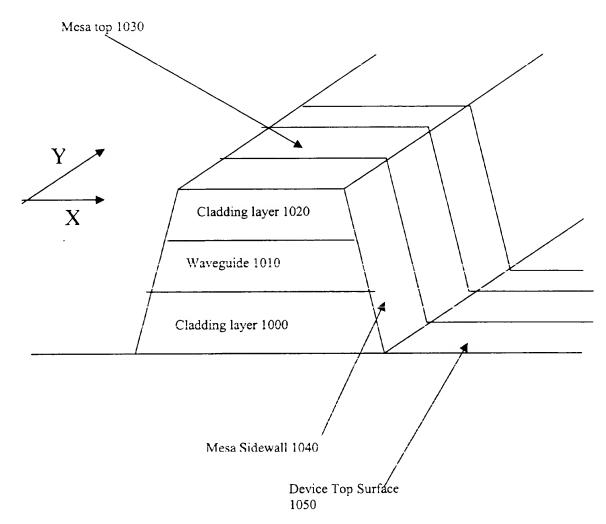


FIG. 22

Create a first cladding layer (Step 910). Create a grating layer (Step 920). Create a hole confinement region layer (Step 930). Create an electron confinement region layer (Step 940). Create a second cladding layer (Step 950). (Optional) Pattern laser structure and additional device processing (Step 960).

FIG. 23